

HOSTAFORM[®] C 9021 XAP[®] C HOSTAFORM®

POM copolymer Medium flow injection molding grade with very low emissions and migrations; designed for consumer packaging. Emission according to VDA 275 < 2 mg/kg (natural grades), VDA 275 < 5 mg/kg (colors), Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470 FDA = Food and Drug Administration (USA)

Product information

Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate	8	cm ³ /10min	ISO 1133
Temperature	190		130 1133
Load	2.16		
Moulding shrinkage, parallel	2.0	•	ISO 294-4, 2577
Moulding shrinkage, normal	1.8		ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	2850	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min		MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	30	%	ISO 527-1/-2
Flexural modulus	2700	MPa	ISO 178
Flexural strength	89	MPa	ISO 178
Tensile creep modulus, 1h	2500	MPa	ISO 899-1
Tensile creep modulus, 1000h	1300		ISO 899-1
Charpy impact strength, 23°C	220 ^[P]	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	220	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30 °C	6	kJ/m²	ISO 179/1eA
Ball indentation hardness, H 358/30		MPa	ISO 2039-1
Poisson's ratio	0.37 ^[C]		
[P]: Partial Break			
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	104	°C	ISO 75-1/-2
Coefficient of linear thermal expansion	110	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE),	110	E-6/K	ISO 11359-1/-2
normal			
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Effective thermal diffusivity, flow	4.85E-8		ISO 22007-4
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

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Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112
Physical/Other properties			
Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m³	ISO 1183
Injection			
Drying Recommended	no		
Drying Temperature	100	°C	
Drying Time, Dehumidified Dryer	3 - 4	h	
Processing Moisture Content	≤0.2	%	
Melt Temperature Optimum	200	°C	
Min. melt temperature	190	°C	
Max. melt temperature	210	°C	
Screw tangential speed	≤0.3	m/s	
Mold Temperature Optimum	100	°C	
Min. mould temperature	80	°C	
Max. mould temperature	120	°C	
Hold pressure range	60 - 120	MPa	
Back pressure	4	MPa	
Ejection temperature	140	°C	

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions

Additional information

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Storage

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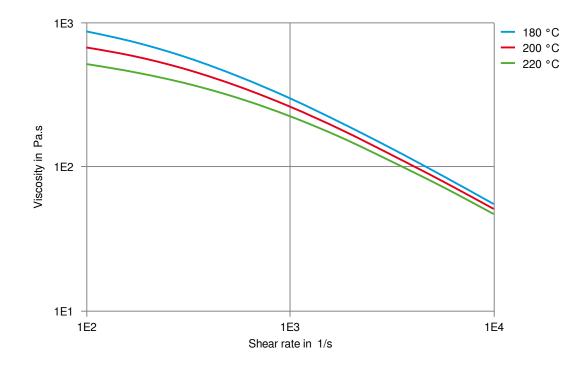




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The product can then be stored in standard conditions until processed.

Viscosity-shear rate

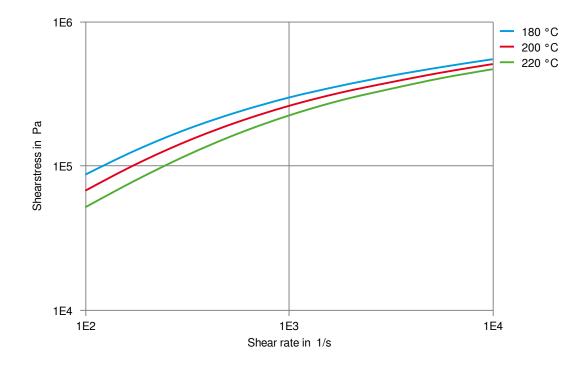






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Shearstress-shear rate

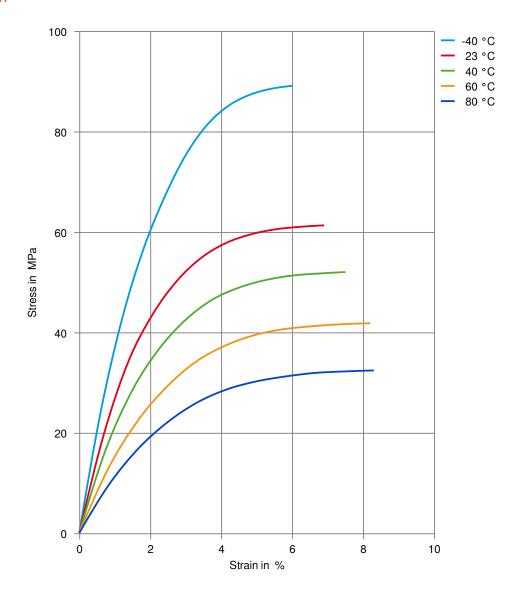






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Stress-strain

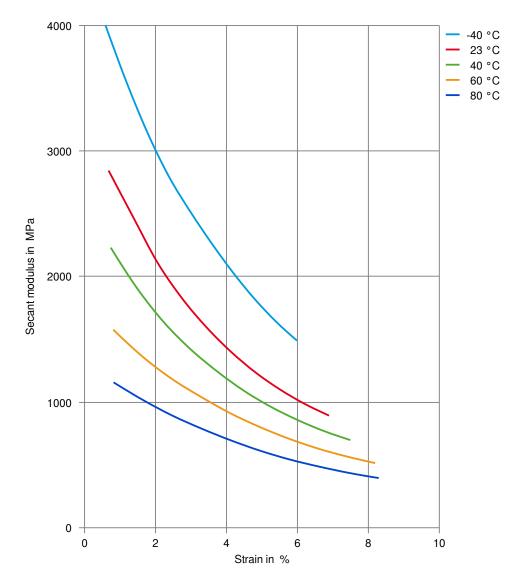






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Secant modulus-strain

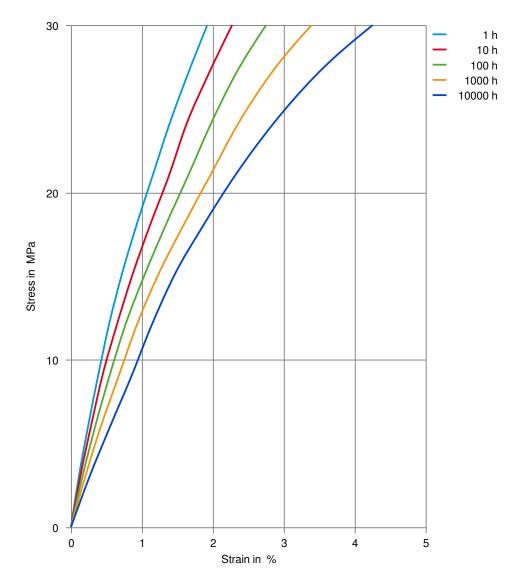






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Stress-strain (isochronous) 23°C

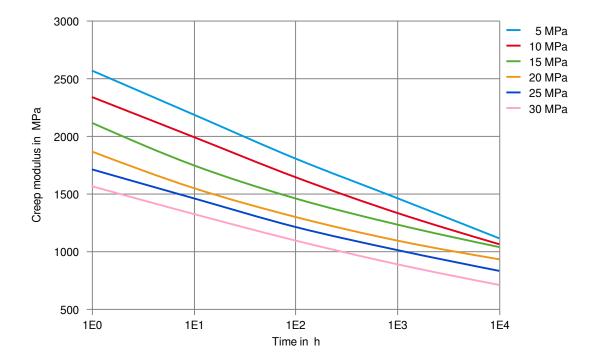






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Creep modulus-time 23°C



Printed: 2025-05-30

Page: 8 of 8

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